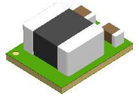
DATA BOOK
PACKAGE OUTLINE

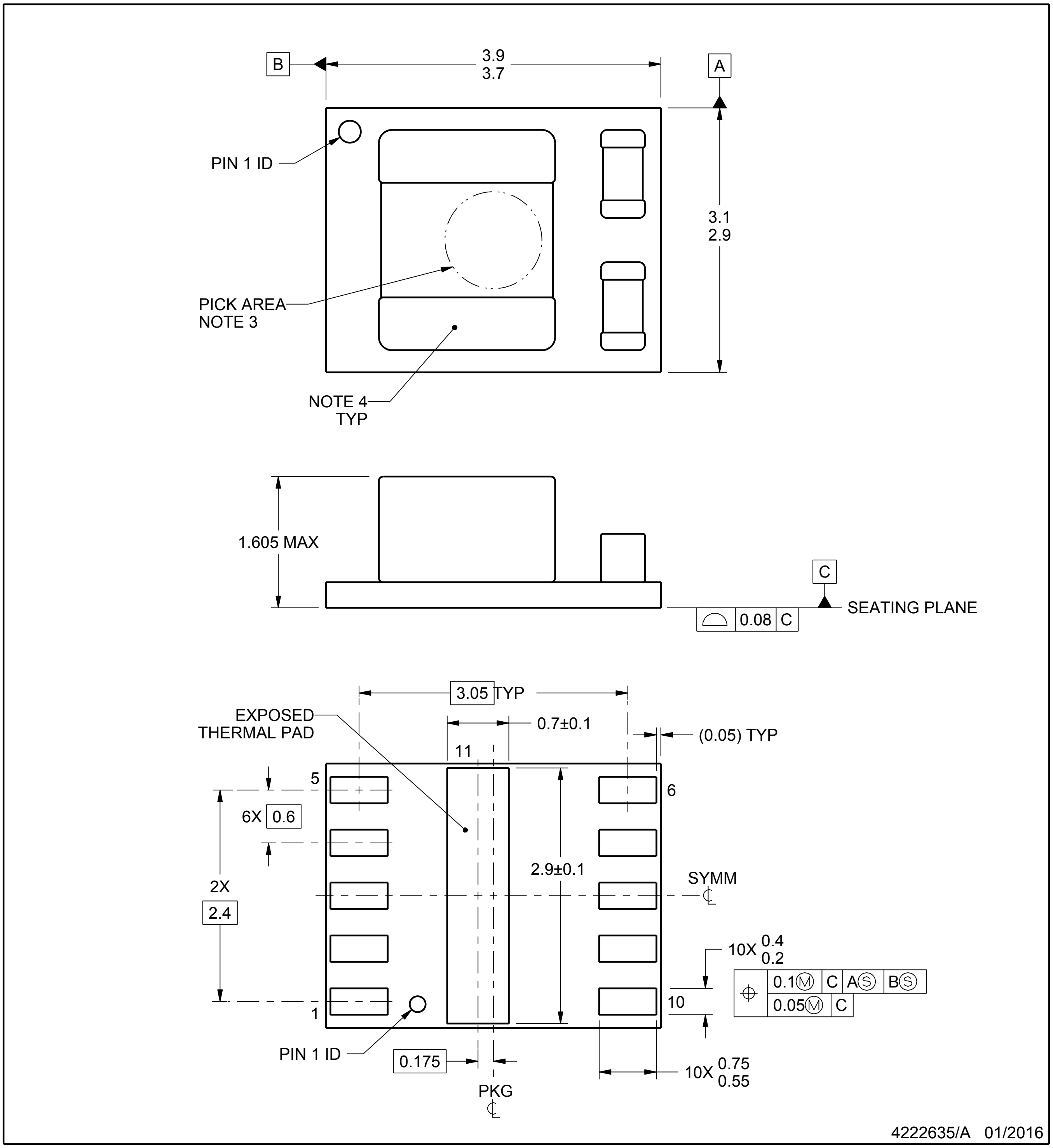
DRAFTER:	T. LEQUANG	DATE:	01/08/2016	DIMENSIONS IN MILLIMETERS
DESIGNER:		DATE:		TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS CODE IDENTITY NUMBER 01295
CHECKER:	K. SINCERBOX & V. PAKU	DATE:	01/08/2016	
ENGINEER:	M. SAMADZADA	DATE:	01/08/2016	ePOD, SIL0010A / MicroSiP, 10 PIN, 0.6 MM PITCH
APPROVED:	E. REY	DATE:	01/08/2016	
RELEASED:	WDM	DATE:	01/08/2016	
TEMPLATE INFO:	EDGE# 4218519	DATE:	03/20/2013	SCALE 15X · SIZE A · 4222635 · REV A · PAGE 1 OF 5



PACKAGE OUTLINE

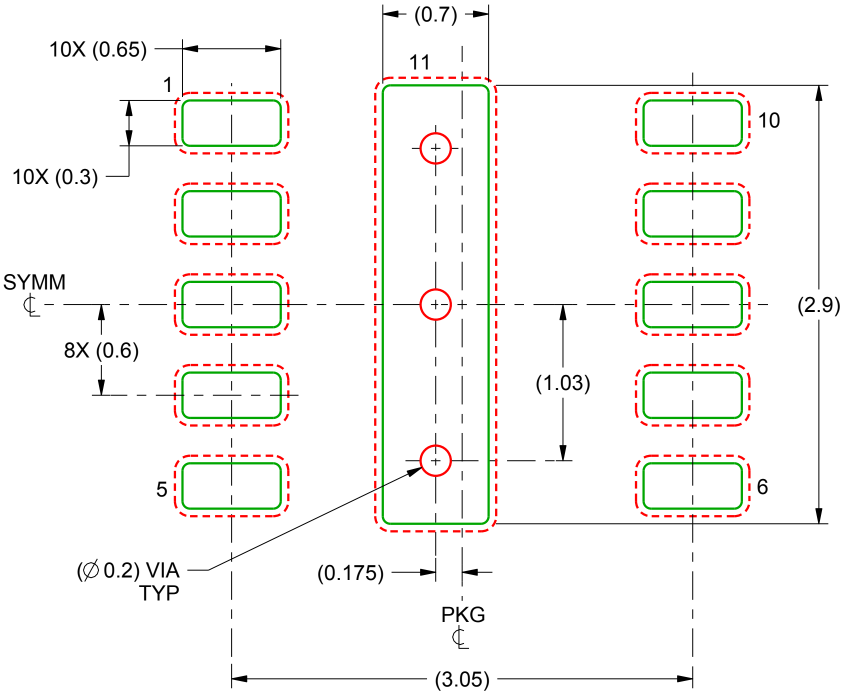
MicroSiP ™ - 1.605 mm max height

MICRO SYSTEM IN PACKAGE

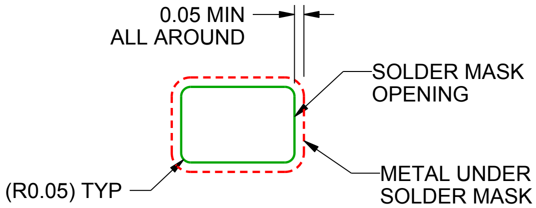


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Pick and place nozzle ∅1.1 mm or smaller recommended.
4. Location, size and quantity of components are for reference only and could vary.
5. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
1:1 RATIO WITH PACKAGE SOLDER PADS
SOLDER MASK DEFINED
SCALE:20X



DETAIL
NOT TO SCALE

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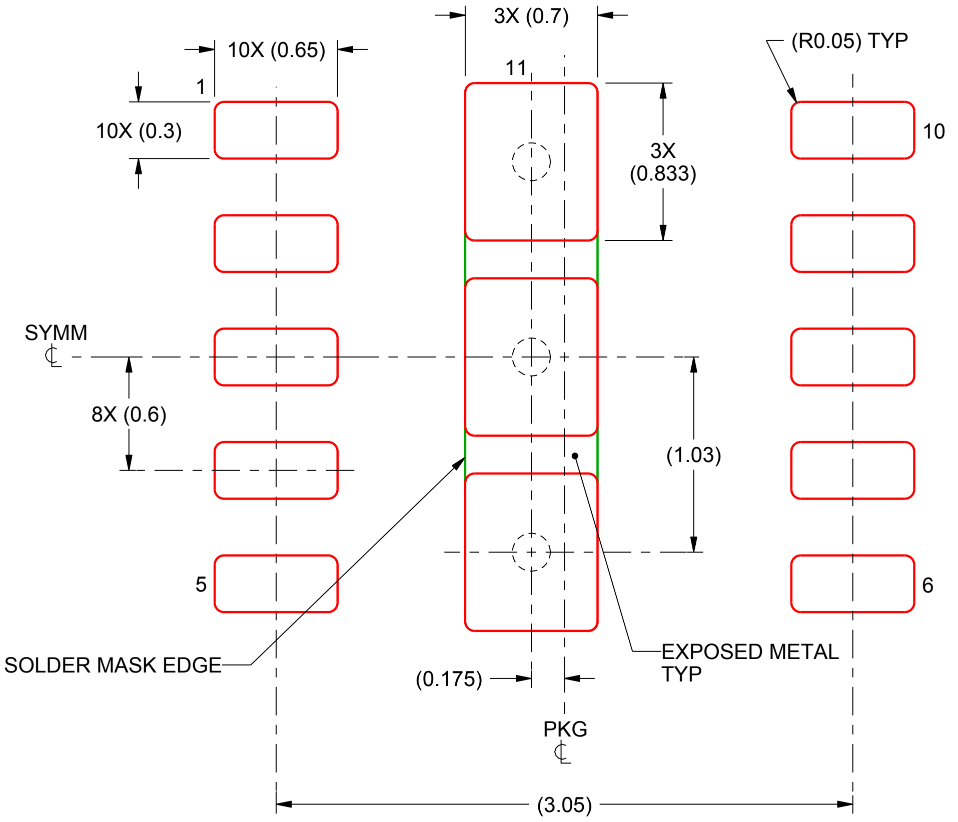
NOTES: (continued)

6. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

PAD 11:
86% PRINTED SOLDER COVERAGE BY AREA
SCALE:25X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2154804	01/08/2016	M. SAMADZADA / T. LEQUANG

SCALE	SIZE		REV	PAGE
	A	4222635	A	5 OF 5